07-31-2001

FORM PTO-1596
1-31-92

Docket No.: 50090-312

101792975

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Parties:

Hisaya Mori, Teruhiko FUNAKURA, and Shinji YAMADA

07/16/01

Additional names of conveying parties attached? ☐ Yes

2. Name and address of receiving parties:

Name: MITSUBISHI DENKI KABUSHIKI KAISHA
Address: 2-3, Marunouchi 2-Chome
Chiyoda-Ku
Tokyo 100-8310 JAPAN

Name: RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION
Address: 1 Mizuhara 4-Chome
Itami-Shi, Hyogo 664-0005 JAPAN

JC821 U.S. PTO
09/904625
07/16/01

Additional names & addresses attached? ☐ Yes

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: June 12, 2001, June 13, 2001, and June 13, 2001

4. Application number or patent number:

If the document is being filed together with a new application, the execution date of the application is: June 12, 2001, June 13, 2001, and June 13, 2001

A. Patent Application No.

09/904625

B. Patent No.

Additional numbers attached? ☐ Yes

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY
Internal Address:
Street Address: 600 13th Street, N.W.
City: Washington State: DC Zip: 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) $40.00

☐ Enclosed
☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Stephen A. Becker, No. 26,527
Name and Registration No. of Person Signing

Signature

July 16, 2001
Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Hisaya MORI (2) Shinji YAMADA
(3) Teruhiko FUNAKURA

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Mitsubishi Denki Kabushiki Kaisha
2-3, Marunouchi 2-chome
Chiyoda-ku, Tokyo 100-8310
JAPAN

and

Ryoden Semiconductor System Engineering Corporation
1 Mizuhara 4-chome
Itami-shi, Hyogo 664-0005
JAPAN

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

TESTER FOR SEMICONDUCTOR INTEGRATED CIRCUITS AND METHOD FOR TESTING SEMICONDUCTOR INTEGRATED CIRCUITS

for which an application for United States Letters Patent was executed on even date herewith,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the international Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) Hisaya Mori Name: Hisaya MORI	June 12, 2001
2) Shinji Yamada Name: Shinji YAMADA	June 13, 2001
3) Teruhiko Funakura Name: Teruhiko FUNAKURA	June 13, 2001